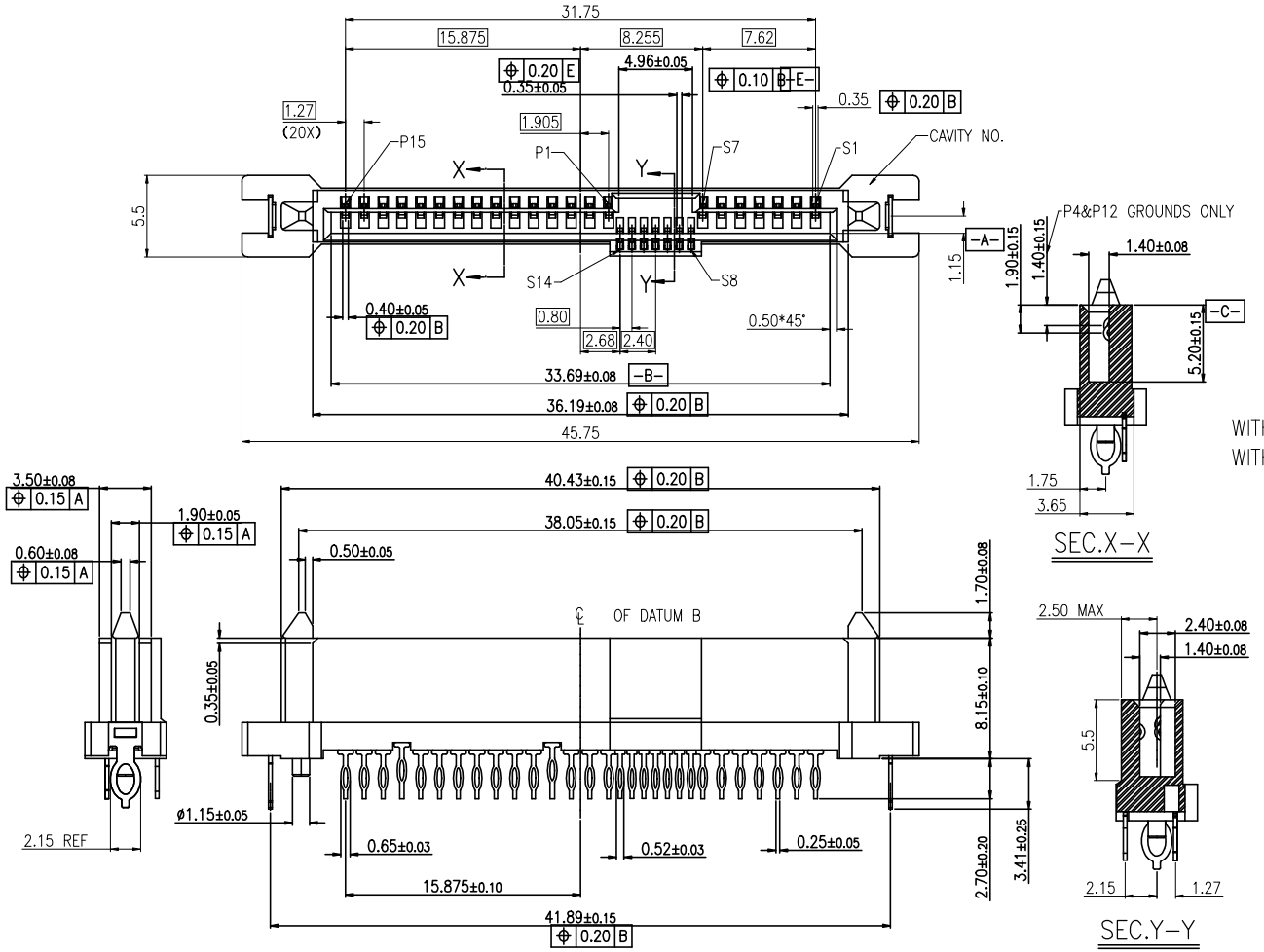
REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
D		调整电气性能描述&更新图框	2021.11.13	XUETAOGUO



NOTE:

1.MATERIAL: SEE BOM

2. SPEC. PLS. REFER TO EI102:
   - DIM. MARKED (XX) SHOULD BE MEASURED BY FAI;
   - DIM. MARKED (C) SHOULD BE CONTROLLED BY QC;
   - DIM. MARKED (M) SHOULD BE MEASURED TERMLY BY QC;
   - DIM. MARKED (CPK) SHOULD BE ANALYSED TERMLY BY QC;

3.ORDERING INFORMATION:

SA1271 H-XX X X X

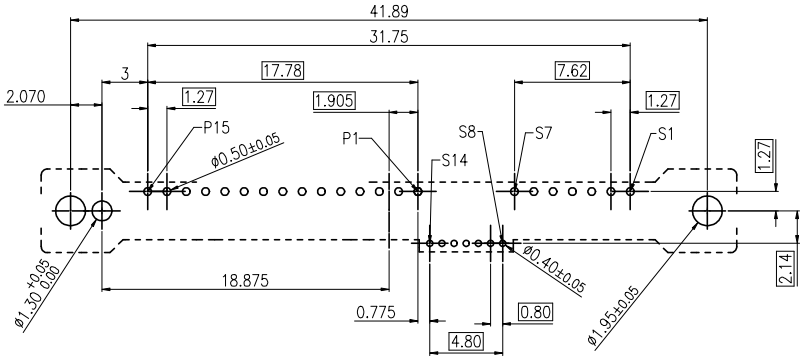
WITHOUT "H" : WITH HALOGEN
WITH "H" : HALOGEN FREE

PIN NO.
29:29P

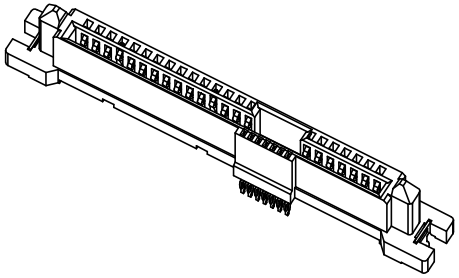
PACKING
3:TRAY

PLATING
TS: 20u"~60u" MATTE TIN PLATING ON SOLDER TAIL AU 3u"/ Pd-Ni10u"ON CONTACT AREA.
T30S: 20u"~60u" MATTE TIN PLATING ON SOLDER TAIL AU 30u"ON CONTACT AREA.

COLOR:
B:BLACK
N:NATURAL



RECOMMENDED SOLDER PAD LAYOUT



NO.	DESCRIPTION	Q'TY.	MATERIAL
3	HOLD DOWN	2	COPPER ALLOY
2	TERMINAL	~	COPPER ALLOY
1	HOUSING	1	HIGH TEMP TERMOPLASTIC UL94-V0 BLACK

一般公差
TOLERANCES
X. ±0.5 .XX ±0.2
.X ±0.25 .XXX ±0.05
ANGLES ±2°

希尔盛精密电子(昆山)有限公司

檢驗尺寸標示
SYMBOLS (C) (M) INDICATE CLASSIFICATION DIMENSION
(C) MARK IS CRITICAL DIM.
(M) MARK IS MAJOR DIM.

品名 (TITLE): 1.27 PITCH SATA CONN

圖號 (DWG NO.): C-SA1271H-XXXXXX

製圖 (DR): XUETAOGUO
審核 (CHKD): LEO-HE
核准 (APPD): LEO-HE

表面處理 (FINISH)

比例 (SCALE): 5:1
單位 (UNITS): mm

張數 (SHEET): 1 OF 1
SIZE: A4
REV: D